



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re Application of:

Moon, et al.

Serial No.: 10/025,144

Confirmation No.: 5051

Filed: December 18, 2001

For: Method and Apparatus for  
Polishing Metal and  
Dielectric Substrates

Group Art Unit: 2813

Examiner: Stephen W. Smoot

Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

CERTIFICATE OF MAILING  
37 CFR 1.8

I hereby certify that this correspondence is being deposited on  
1/27/03 with the United States Postal Service as First Class  
Mail in an envelope addressed to: Commissioner for Patents,  
Washington, D.C. 20231.

1/27/03  
Date

*Kurt H. Smith*  
Signature

RESPONSE TO OFFICE ACTION DATED DECEMBER 27, 2002

In response to the Office Action dated December 27, 2002, having a shortened statutory period for response set to expire on January 27, 2003, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no fee is due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/5999/CMP/CMP/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

THE PENDING CLAIMS:

1. A method for processing a substrate, comprising:  
positioning a substrate having a conductive material formed thereon in a polishing apparatus having one or more rotational carrier heads and one or more rotatable platens, wherein the carrier head comprises a retaining ring and a membrane